

***Electron-Beam Fabrication of Gray-Scale
Occulting Spots in High-Energy Beam
Sensitive (HEBS) Glass***

Daniel Wilson, Paul Maker, Richard Muller,
John Trauger, and Tony Hull

*Jet Propulsion Laboratory
California Institute of Technology
Pasadena, California*

Introduction

Objective

- Fabricate gray-scale occulting spots for coronagraphic telescopes

Approach

- Electron-beam exposure of high-energy beam sensitive (HEBS) glass (product of Canyon Materials, Inc., San Diego, CA)
 - Calibrate transmittance of HEBS glass (measure optical density as a function of electron dose and acceleration voltage)
 - Determine strength and functional form of E-beam proximity effect (exposure due to scattered electrons)
 - Determine limitations imposed by E-beam lithography system (job file parameter limits, clock quantization,)

Introduction

What we have learned so far

- HEBS glass can be darkened to optical density 8 (OD 7.66 achieved without saturation)
 - Requires extra thick sensitive layer (~10 μm) and 100kV electron exposure
 - Optical density vs. E-beam dose can be calibrated accurately
 - There is significant graying around the primary exposure due to scattered electrons (“proximity effect”). This has the *desirable* effect of smoothing the occulting spot profile.
- Electron-beam writing parameters can be selected to accurately represent the desired spot functions
 - Dose quantization error $\ll 1\%$ at high doses, $<1\%$ at low doses
- Need to improve occulting spot characterization techniques to enable accurate comparison of fabricated spots to desired functional forms
- Need to determine the effects of radiation on HEBS glass

Occulting Spot Specifications

Desired Specifications

- Minimum transmittance at center of spot
 - Intensity transmittance, $T < 10^{-8}$
 - Optical density, $OD = -\log(T) > 8$
- Functional form accuracy (Gaussian, sinc^2 , etc.)
 - Amplitude transmittance error $< 1 \times 10^4$ (under investigation)
 - Spatial pattern pixel size $<$ wavelength (~ 800 nm) to avoid diffraction of light into planet detection regions

Electron-Beam Exposure of HEBS Glass

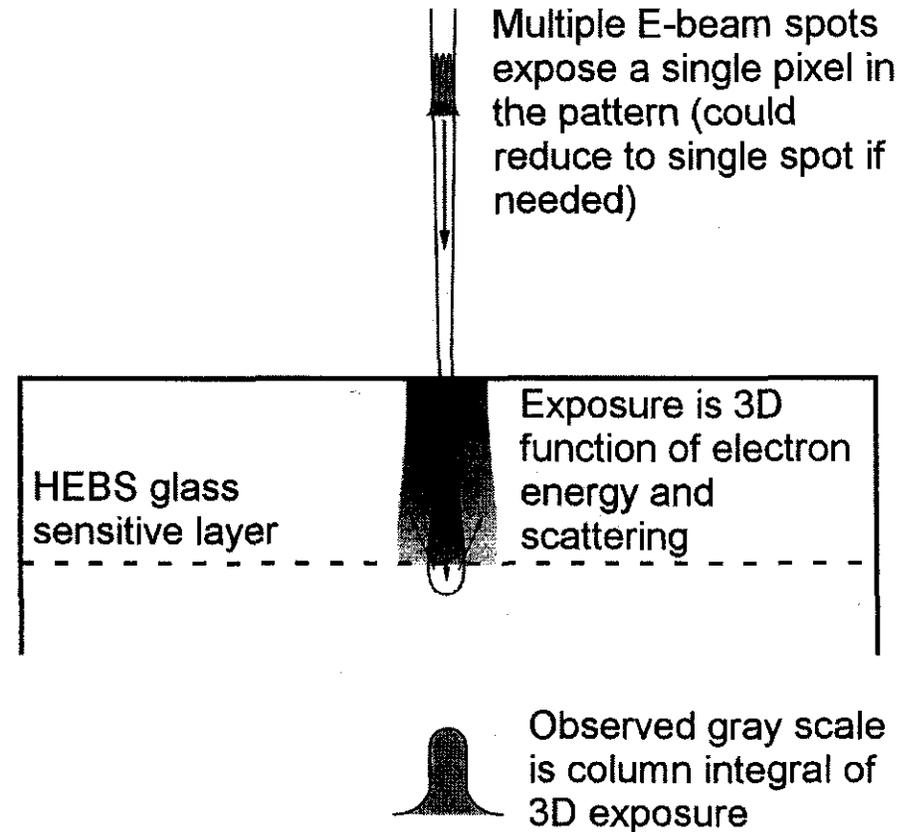
Gray-scale occulting spot fabrication method

- High energy beam sensitive (HEBS) glass (~~product of Canyon Materials, San Diego, CA~~)
 - Low expansion zinc-borosilicate glass doped (ion-exchanged) with silver ion containing complex crystals and photo inhibitors
 - Silver ion complex crystals gray with electron-beam exposure
 - Sensitive layer is typically 3 μm thick
 - We ordered a special lot with sensitive layer $\sim 10 \mu\text{m}$ thick to maximize optical density with 50 or 100 kV electron beam exposures

Electron-Beam Exposure of HEBS Glass

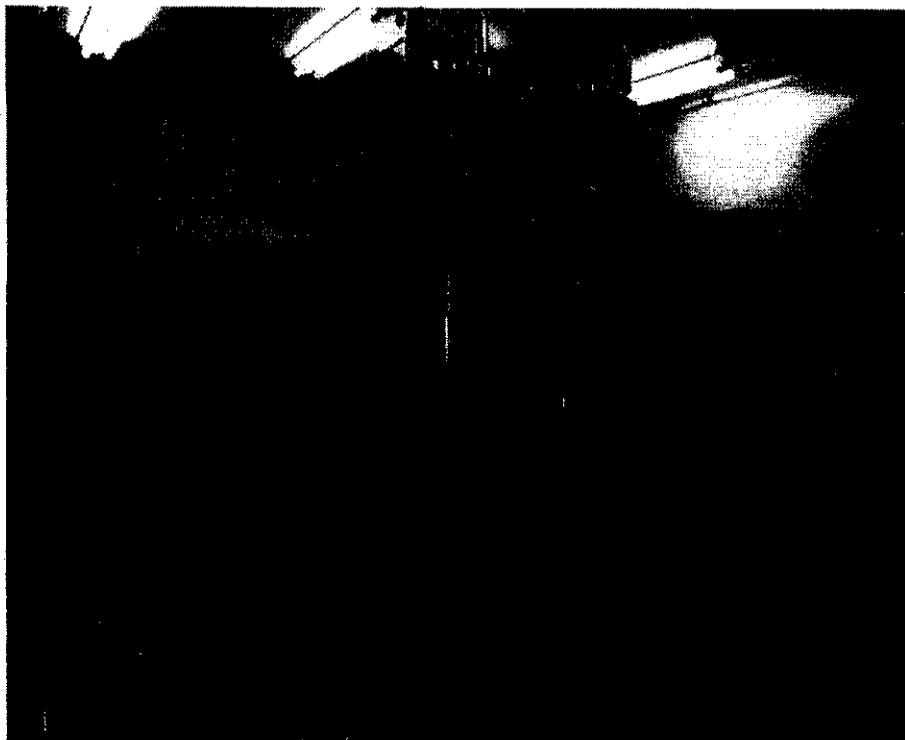
Gray-scale occulting spot fabrication method

- Electron-beam exposure
 - JEOL 9300FS at JPL (50 or 100 kV acceleration voltage)
 - Electrons scatter and slow as they penetrate the glass, resulting in graying around primary spot (“proximity effect”) and non-uniform graying as a function of depth (not yet characterized, experiment in progress)



E-Beam Lithography at JPL

JEOL JBX-9300FS



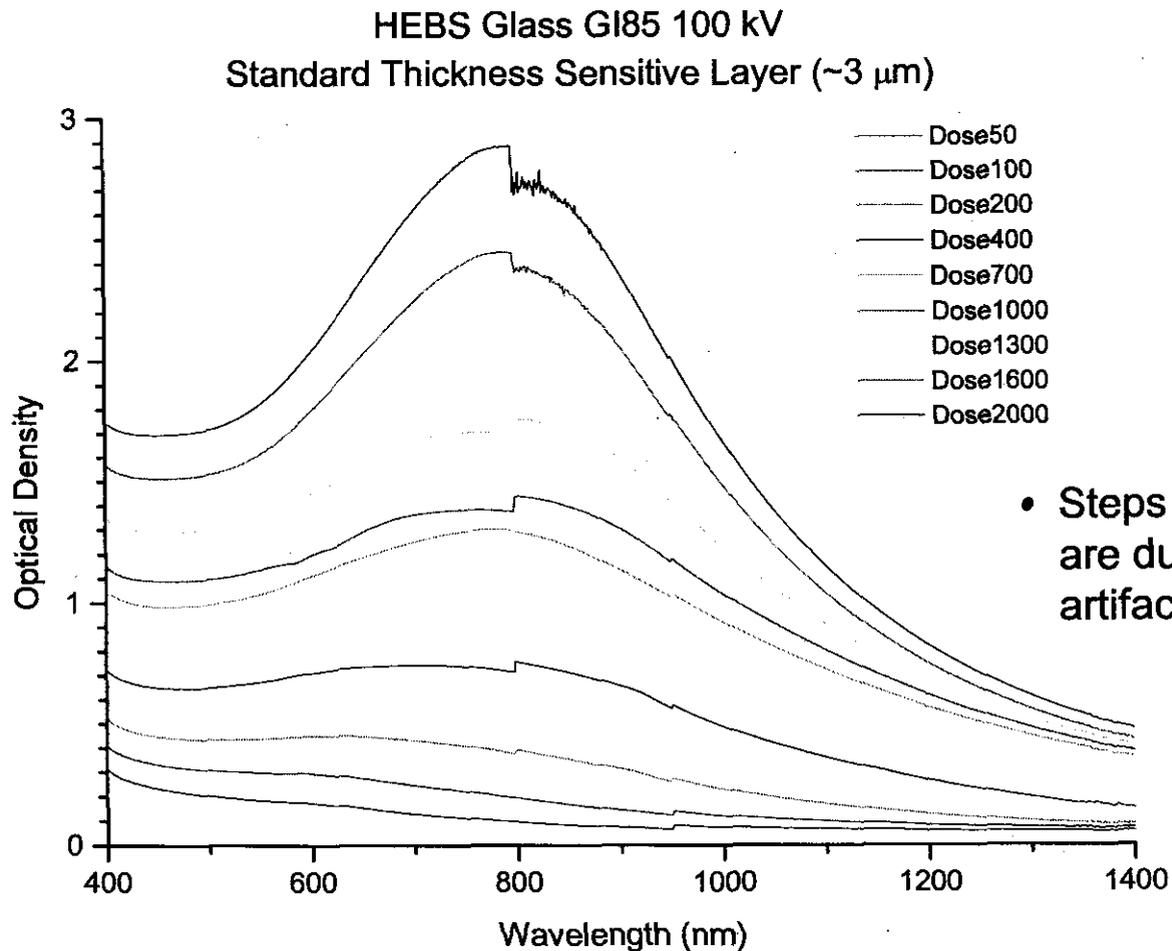
*State-of-the-Art Electron-Beam
Lithography System*

<i>Parameter</i>	<i>JEOL JBX-9300FS</i>	
Voltage	100 kV	50 kV
Minimum Spot Size	4 nm	7 nm
Beam Current for: 100 nm spot	175 nA	125 nA
10 nm spot	10 nA	4 nA
Field Size	500 μm	1000 μm
Pattern Generator Speed	25 MHz	
Field Stitching Accuracy	20 nm	
Write Area	9 in sq	
Wafer Size	12 in dia	
Writing Grid	1 nm	2 nm
Electron Source	ZrO/W Field Emission Gun	
Deflection System	Dual Deflector Low-speed 19-bit DAC High-speed 12-bit DAC Dynamic focus Dynamic astigmatism	
Fine-Pitch Control	$\pm 5\%$	
Height Control	White-light measurement Auto-correction direct-write, ± 0.2 mm Manual via Jobdeck, ± 2 mm	
Cabling	Ethernet	
Computer Control	Local Smarts - 3 Internal DEC Alpha CPUs	

HEBS Glass Calibration

Optical density as function of wavelength and dose

- 3 x 3 mm areas exposed and measured with a spectrophotometer
- Peak OD is near 800 nm for 'GI85' glass
- 100 kV electrons go through 3 μm sensitive layer – much more OD possible with a thicker layer

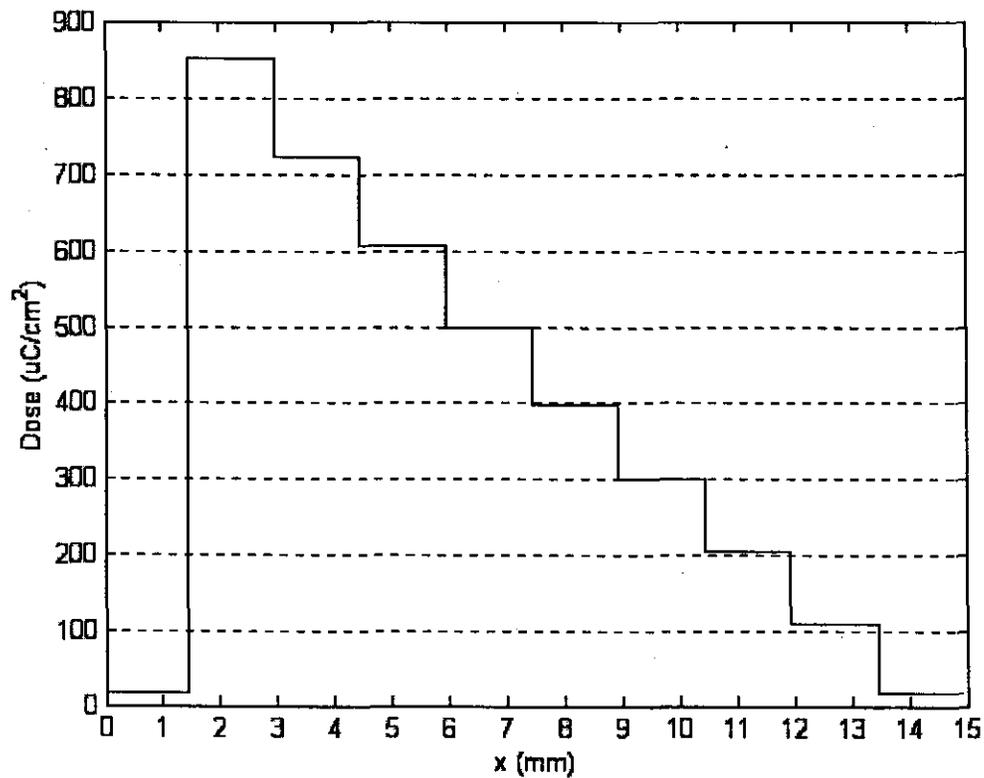
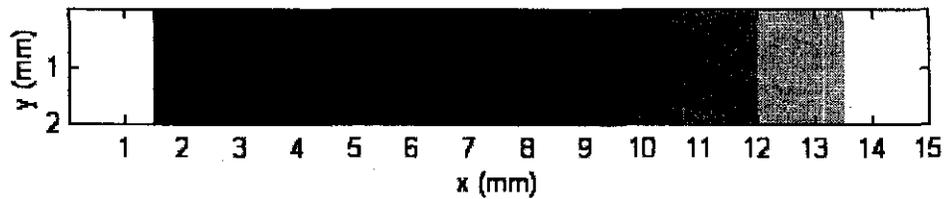


- Steps in OD at 800 nm are due to instrument artifacts (grating changes)

HEBS Glass Calibration

Optical density vs. dose calibration

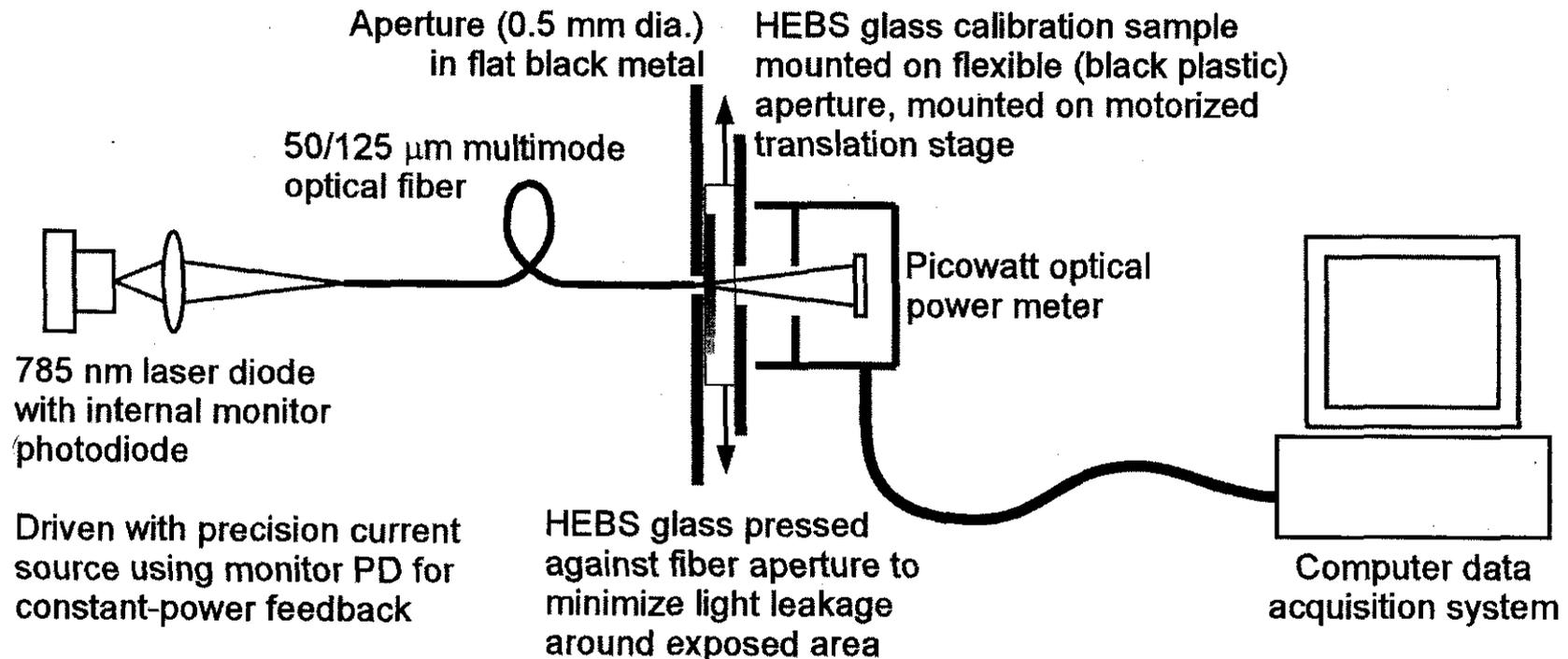
- OD measurements using laser near peak wavelength (785 nm)
- Calibration pattern with constant-dose steps



HEBS Glass Calibration

Optical density vs. dose calibration (cont.)

- Optical density measurement setup

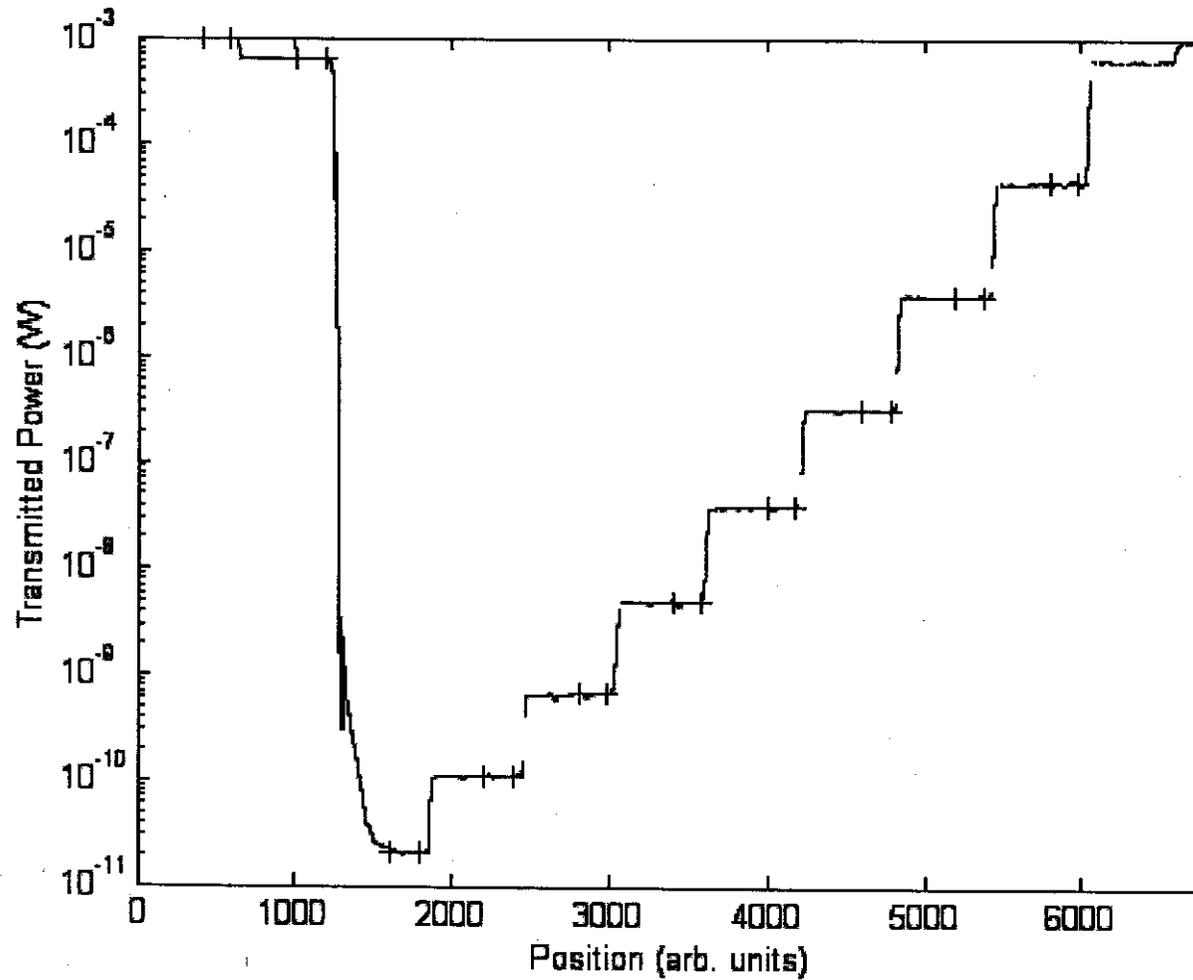


- Optical fiber is convenient for light delivery and provides well-defined source, but end-face reflection and large divergence reduces spatial resolution and maximum OD of setup – will eliminate in future

HEBS Glass Calibration

Optical density vs. dose calibration (cont.)

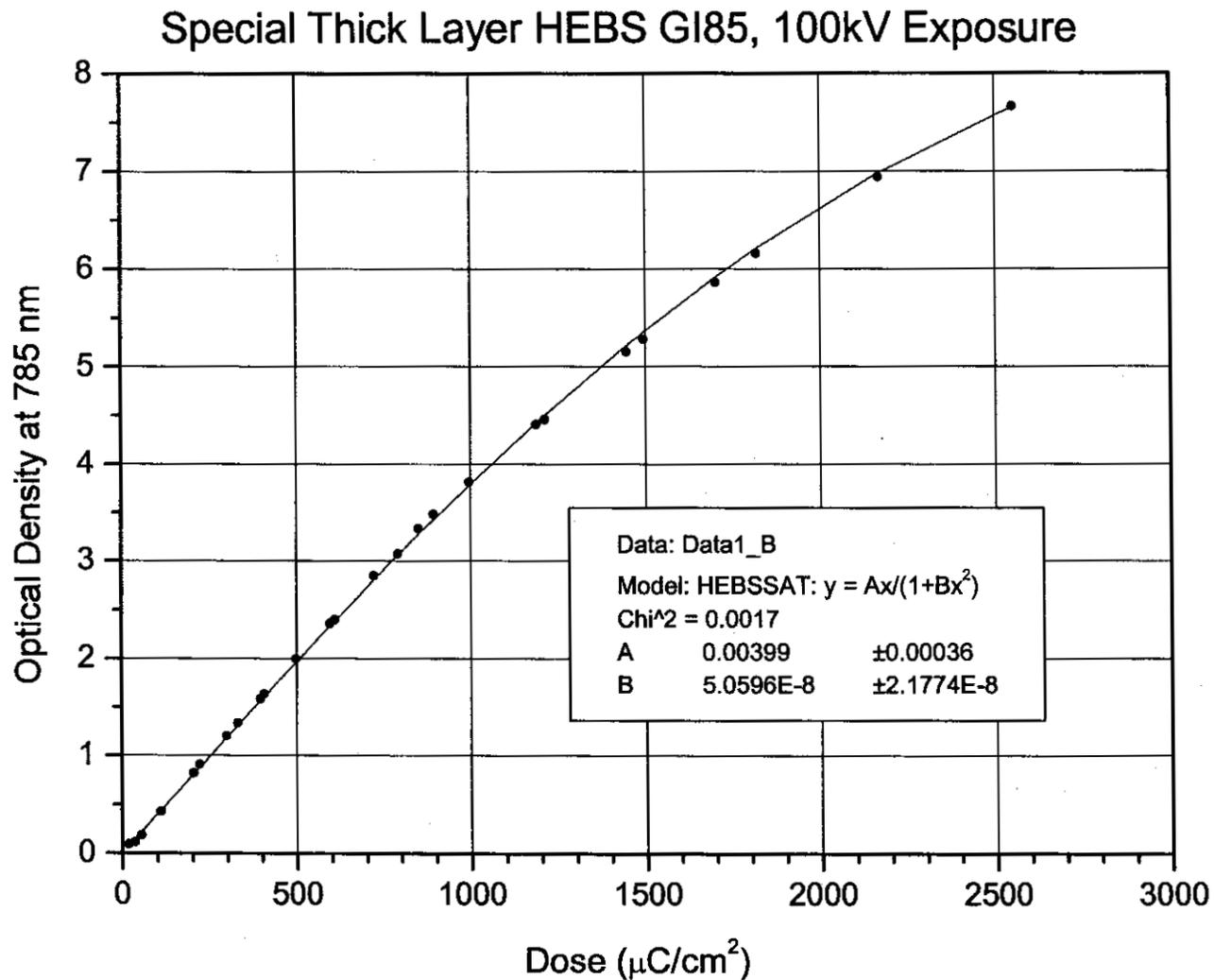
- Experimental data from HEBS glass scan



HEBS Glass Calibration

Optical density vs. dose calibration (cont.)

- OD 8 at 785 nm will be possible with a dose of $\sim 3000 \mu\text{C}/\text{cm}^2$
- Data fit with saturating function to use for converting spot OD functions to dose



Characterization and Compensation of E-Beam Proximity Effect

Proximity effect characterization

- Total dose is convolution of primary dose pattern and point spread function

$$Dose_{total}(\mathbf{r}) = Dose_{primary}(\mathbf{r}) \otimes PSF(\mathbf{r})$$

$$PSF(\mathbf{r}) = \delta(\mathbf{r}) + \frac{\eta}{\pi\alpha^2} \exp(-r^2/\alpha^2)$$

$$\int_{-\infty}^{\infty} PSF(\mathbf{r}) d\mathbf{r} = 1 + \eta$$

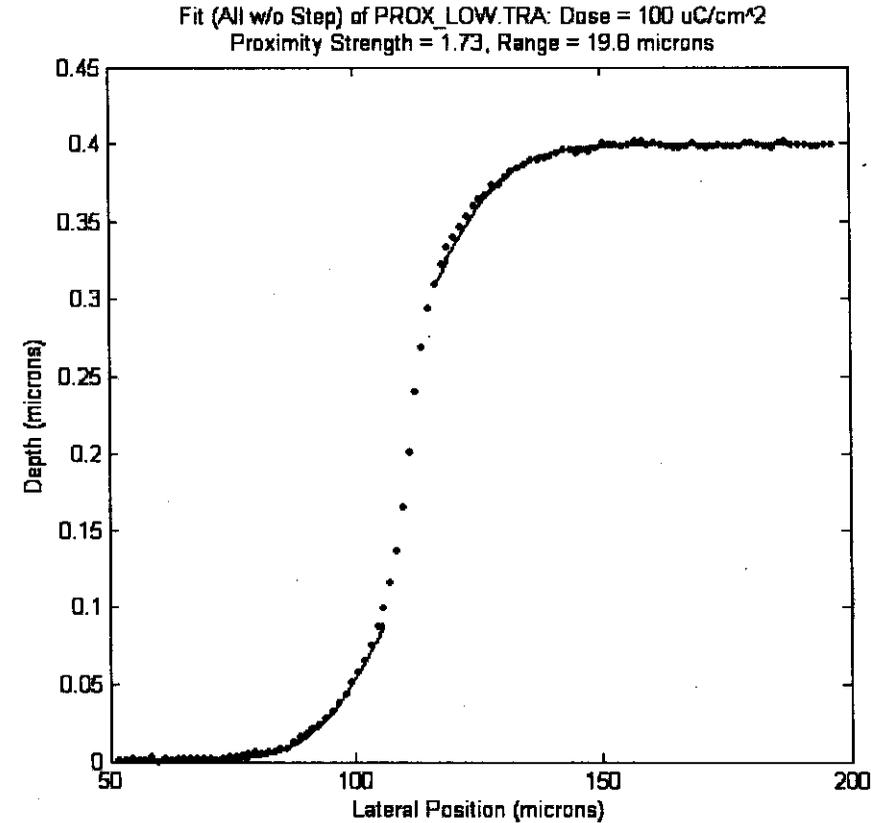
η is "strength", α is "range"

- Analytical convolution of PSF with primary dose step function

$$Dose_{total}(x) = Dose_{primary\ constant} \left\{ \text{step}(x - x_{step}) + \frac{\eta}{2} \left[1 + \text{erf} \left(\frac{x - x_{step}}{\alpha} \right) \right] \right\}$$

- From dose, optical density

$$OD(x) = f\{Dose_{total}(x)\}, \text{ where } f \text{ is } OD \text{ vs. } Dose \text{ calibration curve}$$



Fit of Optical Density Scan at Edge of Uniform Dose Exposure

Characterization and Compensation of E-Beam Proximity Effect

Proximity effect compensation

Given a desired intensity transmittance function $T(\mathbf{r})$

1. Calculate optical density function $OD(\mathbf{r}) = -\log[T(\mathbf{r})]$
2. Use OD vs. dose calibration curve (and proximity strength) to determine desired *total* dose function
3. Deconvolve the proximity effect out of the total dose function to yield the *primary* dose function

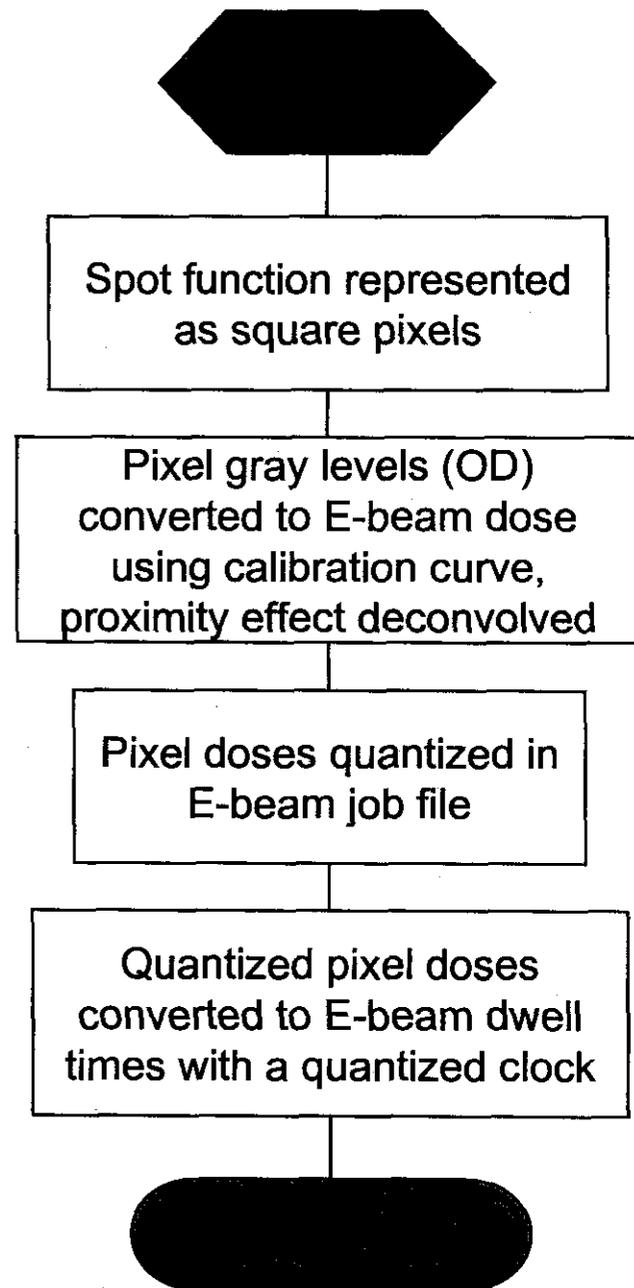
$$D_{\text{primary}}(\mathbf{r}) = F.T.^{-1} \left\{ \frac{F.T.\{D_{\text{total}}(\mathbf{r})\}}{F.T.\{PSF(\mathbf{r})\}} \right\}$$

- Analytical Fourier transform of PSF is used for efficiency
- Zero padding used to prevent periodic effects of FFT

Electron-Beam Exposure Optimization

E-beam pattern preparation

- Optical density of spot function is represented as square pixels with sizes less than wavelength (0.1 to 0.5 μm)
- Pixel optical densities are converted to E-beam doses ($\mu\text{C}/\text{cm}^2$) using OD vs. dose calibration curve and proximity effect is deconvolved from dose pattern
- Doses are quantized to multiples of 0.001 x 'base dose' in job file (typical dose resolution of 0.1 $\mu\text{C}/\text{cm}^2$)
- Doses are converted to E-beam dwell times with a minimum clock resolution of 0.2 ns
- Quantization effects can be minimized by proper selection of job file parameters and background dose



Electron-Beam Exposure Optimization

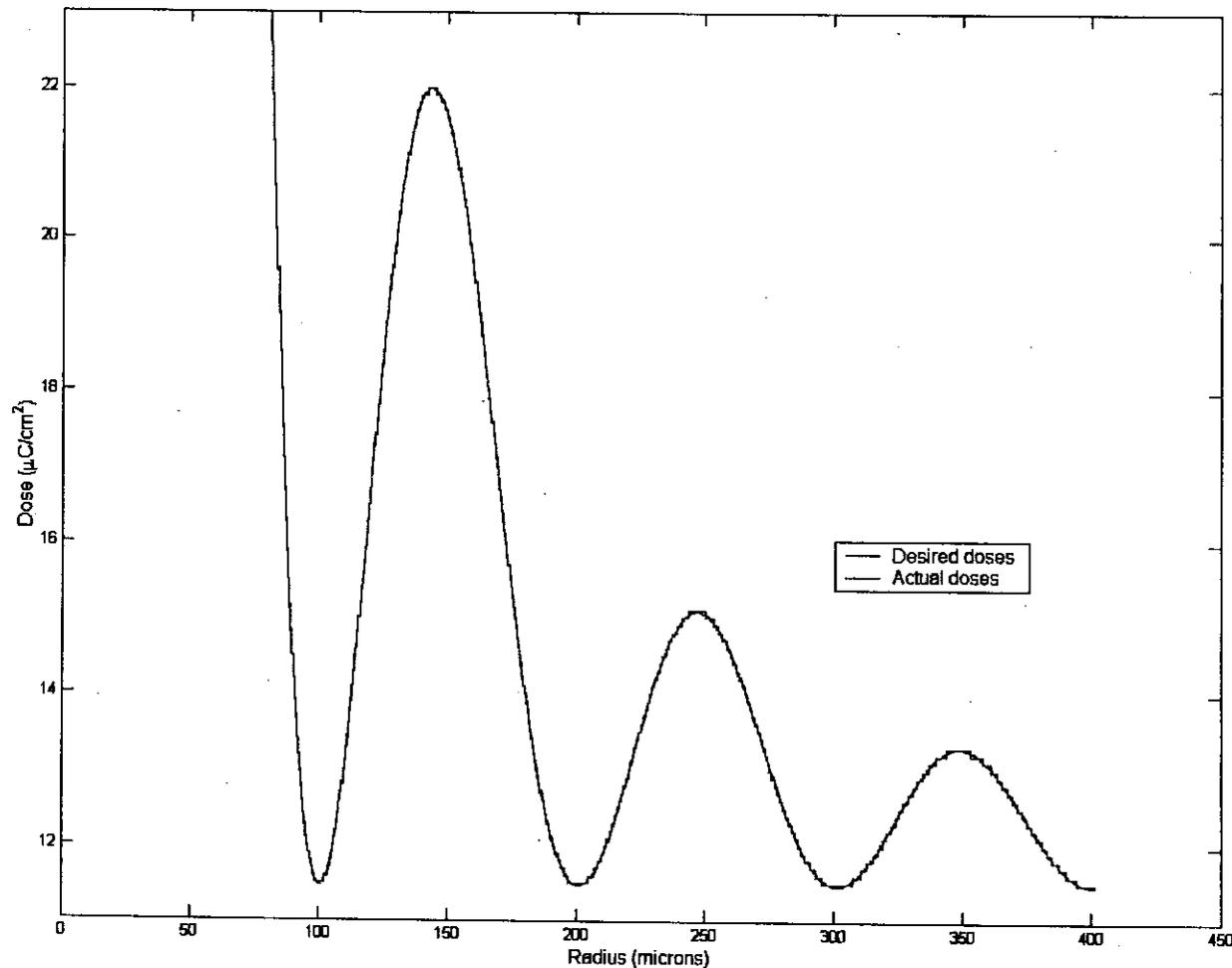
Exposure optimization example

- Job file quantization
 - Using a 'base dose' of $100 \mu\text{C}/\text{cm}^2$, available doses (job file limited) are 0.1, 0.2, 0.3 ... 3299.8, 3299.9, 3300 $\mu\text{C}/\text{cm}^2$ (can achieve desired maximum OD > 8)
 - Using a background dose of $\sim 10 \mu\text{C}/\text{cm}^2$
 - At low doses (max T, edges), functional accuracy is $0.1/10 = 0.01$
 - At high doses (min T, center), functional accuracy is $0.1/3000 = 3.3 \times 10^{-5}$
- Dwell time clock quantization (minimum clock resolution = 0.2 ns)
 - At center of spot, dose = $\sim 3000 \mu\text{C}/\text{cm}^2$, dwell time = 12000 ns, quantization error = $0.2/12000 = 1.7 \times 10^{-5}$ (negligible)
 - At outer radius of spot, dose = $\sim 10 \mu\text{C}/\text{cm}^2$, dwell time = 40 ns, quantization error = $0.2/40 = 0.005$ (less than job file limitation)

Electron-Beam Exposure Optimization

Exposure optimization example (cont.)

- Airy rings of sinc^2 pattern are the only place dose quantization errors are even visible (note that maximum dose is $\sim 3000 \mu\text{C}/\text{cm}^2$ and this plot is in the 11-23 $\mu\text{C}/\text{cm}^2$ range)



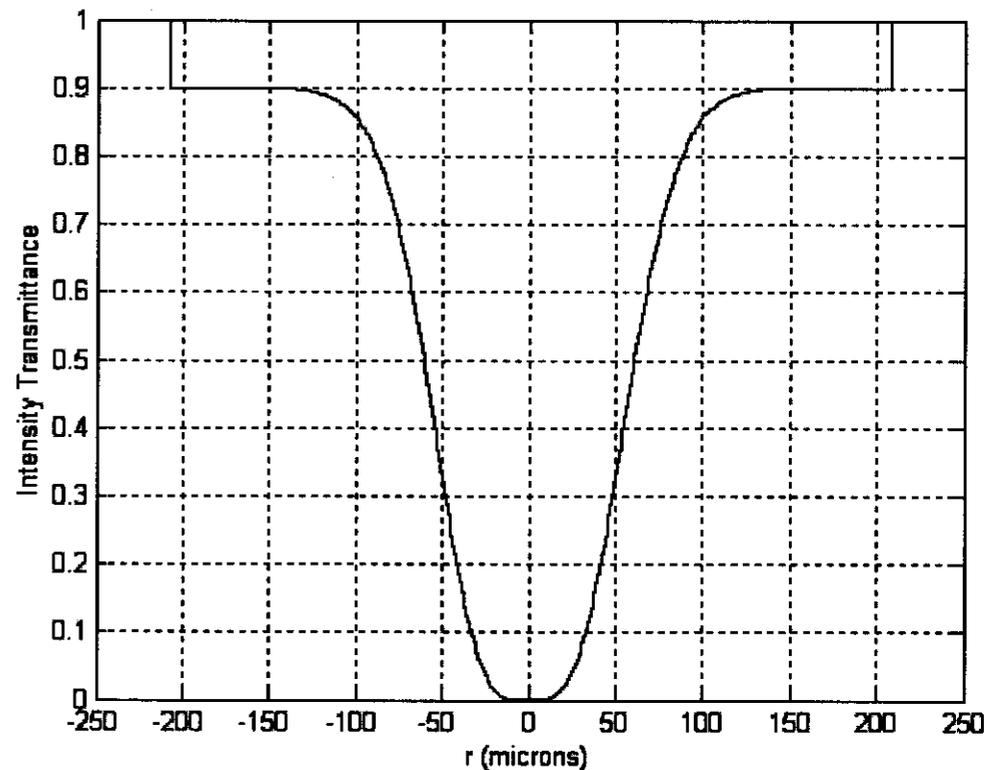
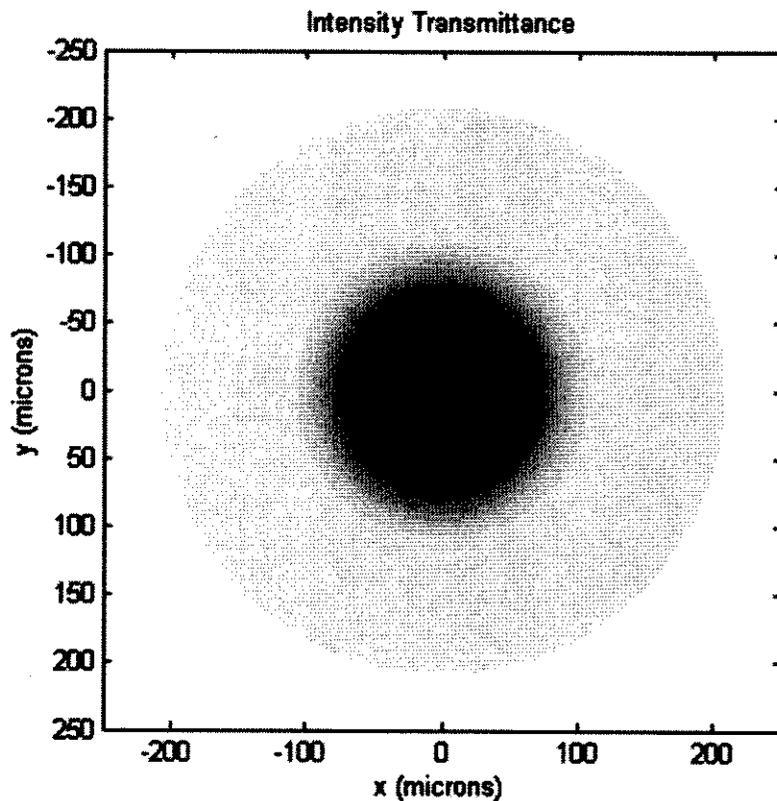
Fabricated Occulting Spot Results

Occulting spot designs

1. Circular Gaussian:

$$T(r) = T_{\max} \left[1 - \alpha e^{-(r/\sigma)^2} \right]^2$$

$$T_{\max} = 0.9, \quad \alpha = 1 \text{ (no OD limit)}, \quad \sigma = 52.0 \text{ } \mu\text{m}, \quad r_{\max} = 4 \times 52 = 208 \text{ } \mu\text{m}$$



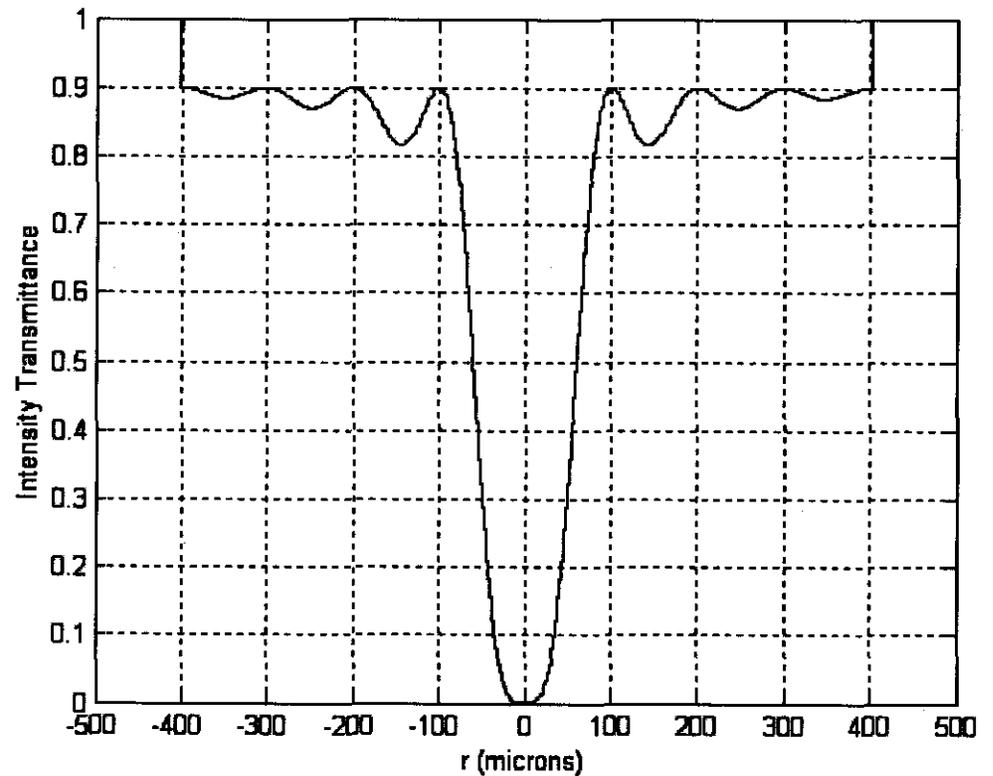
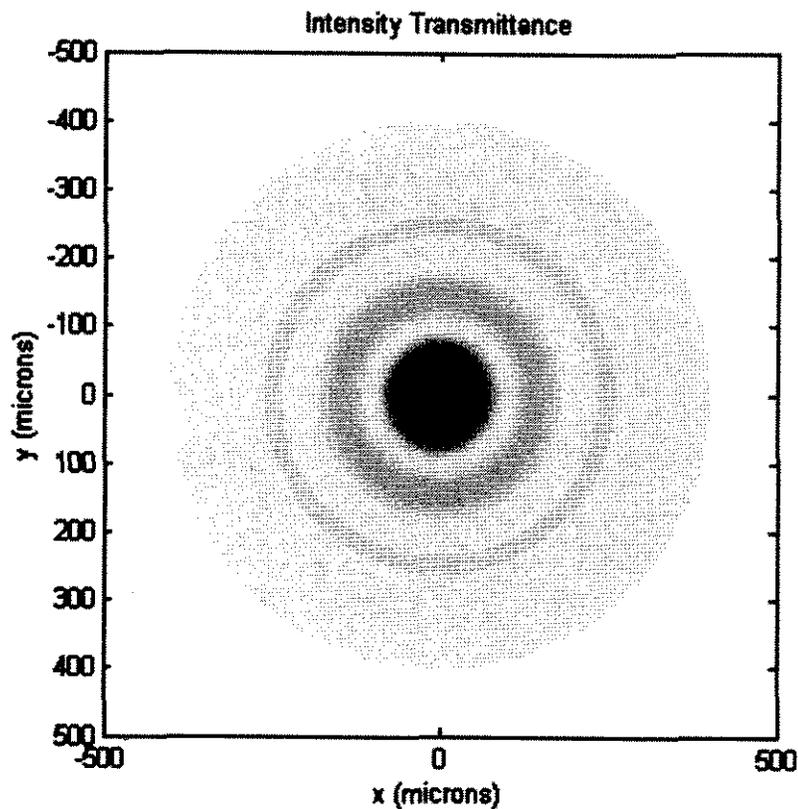
Fabricated Occulting Spot Results

Occulting spot designs (cont.)

2. Circular sinc²:

$$T(r) = T_{\max} \left[1 - \alpha \left[\frac{\sin(\pi r / w)}{\pi r / w} \right]^2 \right]^2$$

$$T_{\max} = 0.9, \quad \alpha = 1 \text{ (no OD limit), } w = 100.5 \text{ } \mu\text{m}, \quad r_{\max} = 4 \times 100.5 = 402.0 \text{ } \mu\text{m}$$



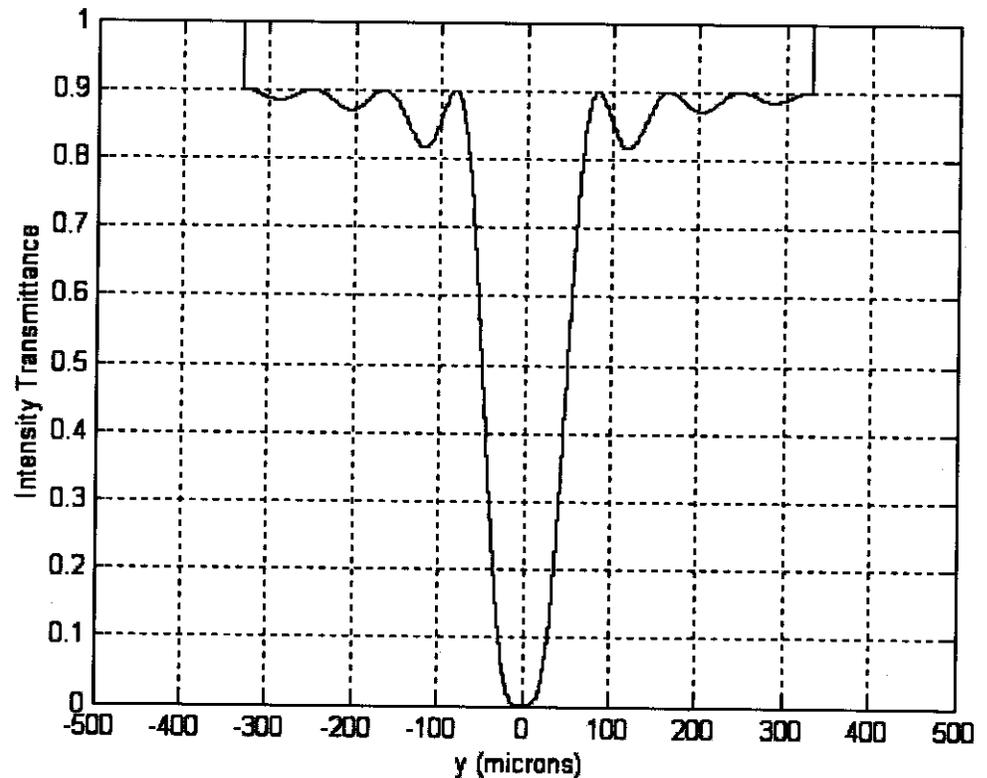
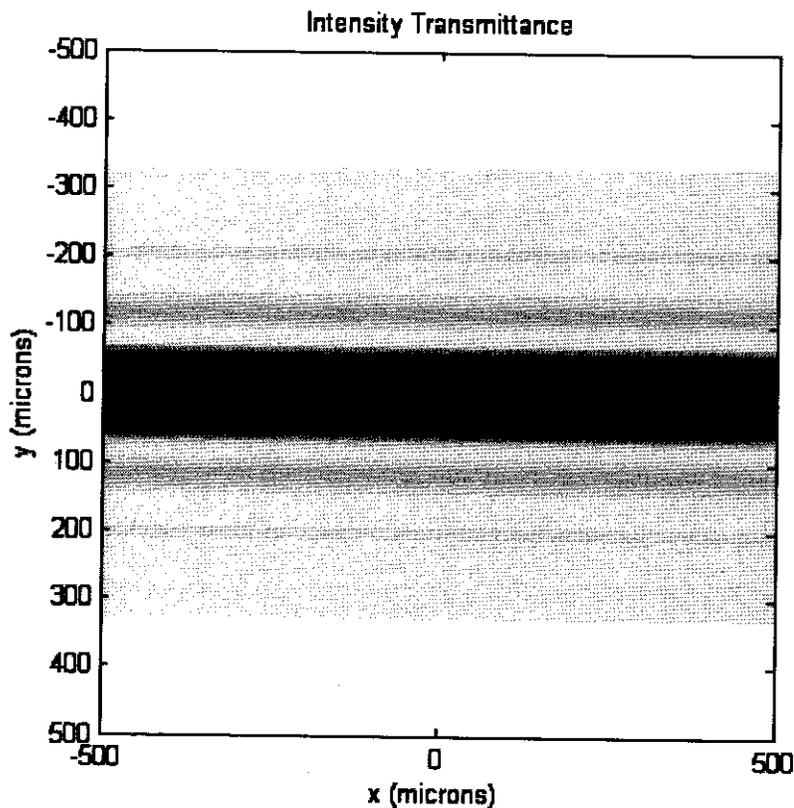
Fabricated Occulting Spot Results

Occulting spot designs (cont.)

3. Linear sinc²:

$$T(x) = T_{\max} \left[1 - \alpha \left[\frac{\sin(\pi x / w)}{\pi x / w} \right]^2 \right]^2$$

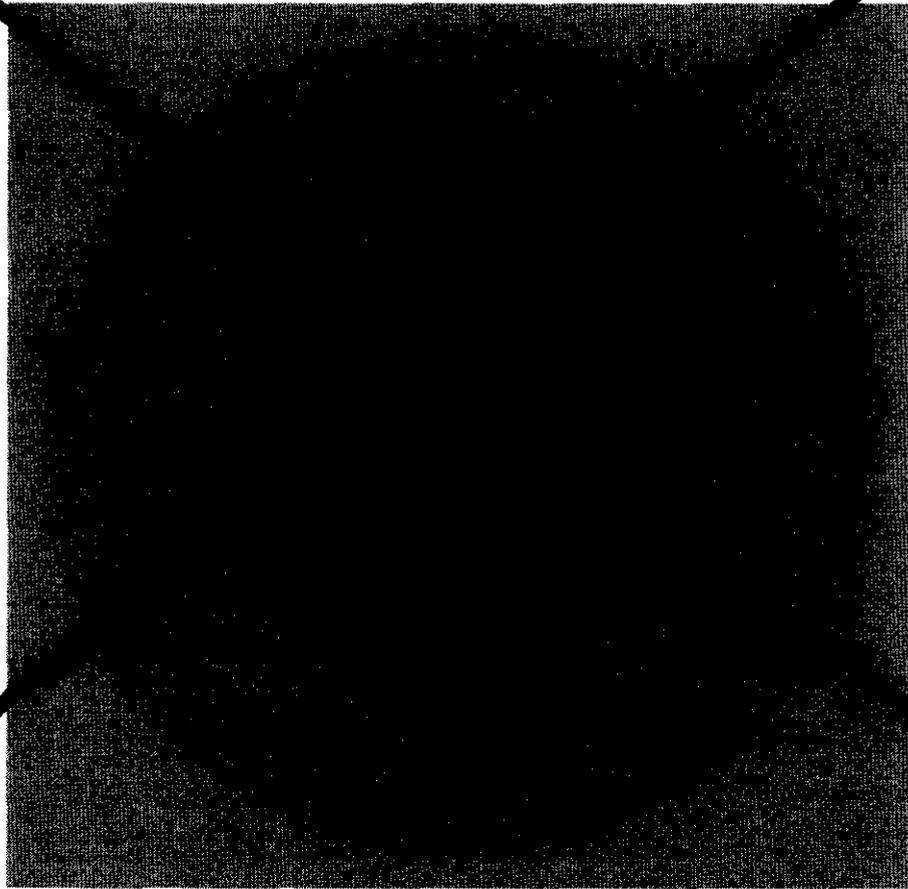
$$T_{\max} = 0.9, \alpha = 1 \text{ (no OD limit), } w = 82.9 \mu\text{m, } x_{\max} = \pm 4 \times 82.9 = \pm 331.6 \mu\text{m}$$



Fabricated Occulting Spot Results

Images of fabricated spots (not corrected for proximity effect)

1. Circular Gaussian

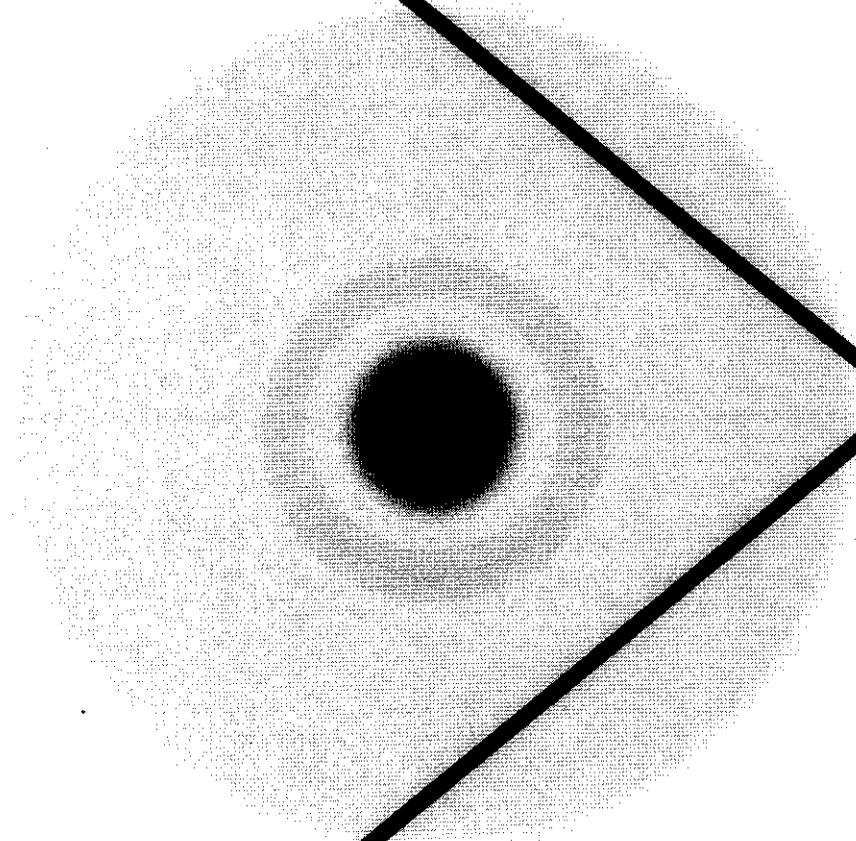


Raw image

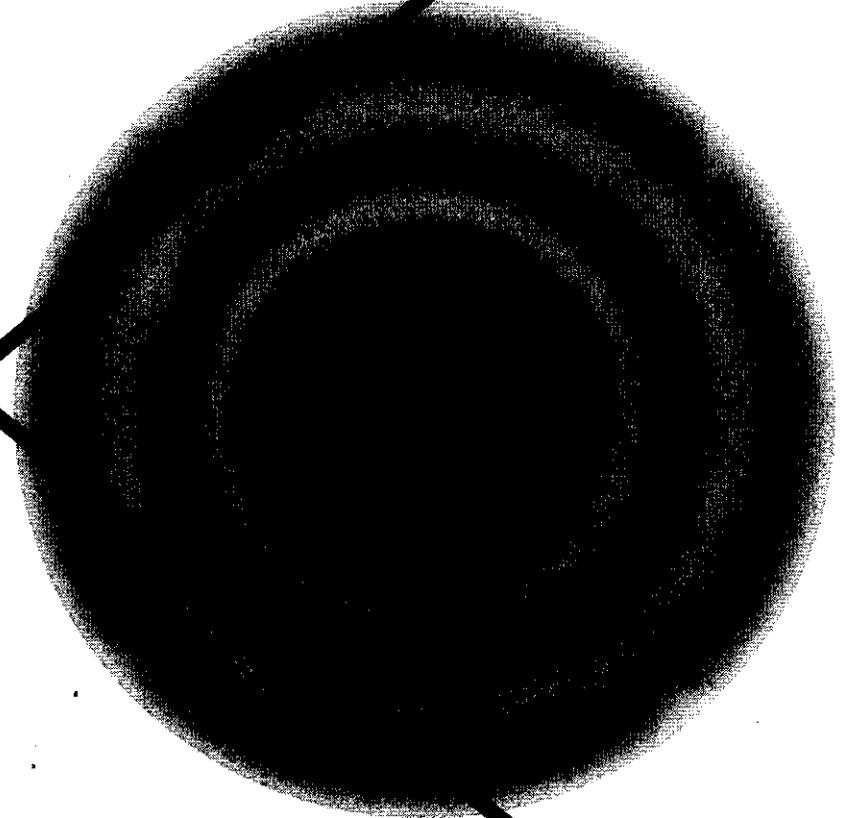
Fabricated Occulting Spot Results

Images of fabricated spots (cont.)

2. Circular SiO_2



Transmittance Image
(Spot image / clear glass)

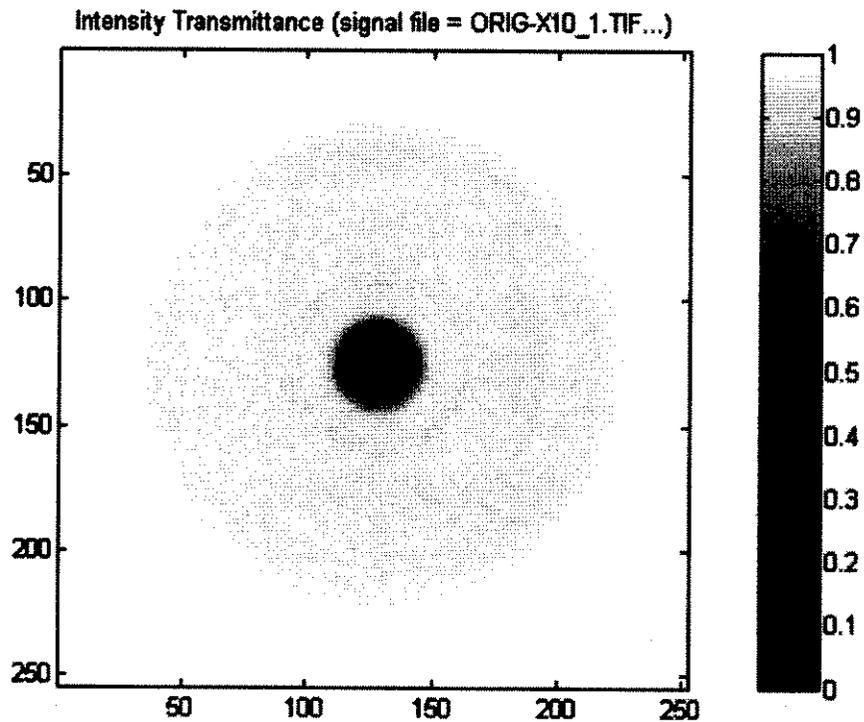


Hard colormap stretch shows
E-beam exposure errors – likely due
to charging of the the HEBS glass

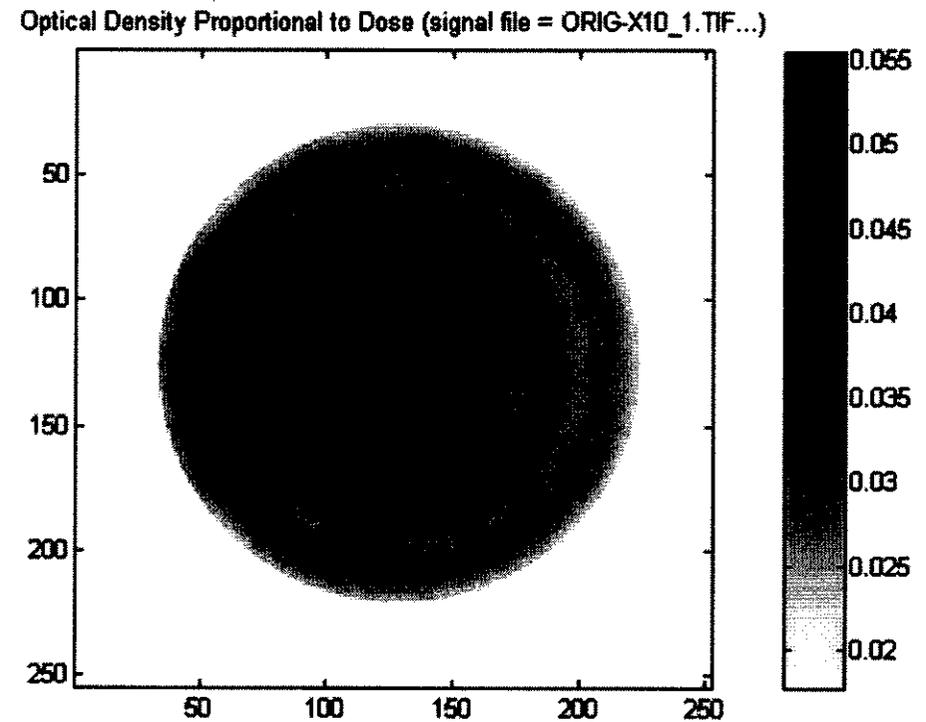
Fabricated Occulting Spot Results

Images of fabricated spots (cont.)

2A. Circular sinc² – Exposed 10 times with 1/10 dose to correct non-uniformity



Transmittance Image
(Spot image / clear glass)

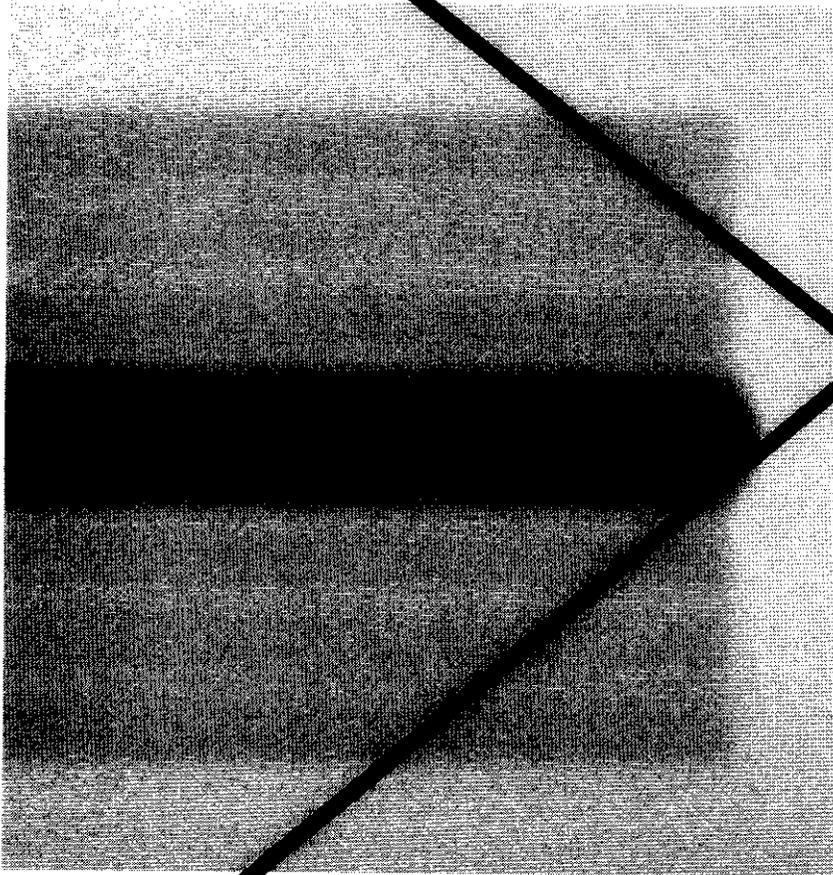


Non-uniformity is corrected
(image is poor due to uncooled camera)

Fabricated Occulting Spot Results

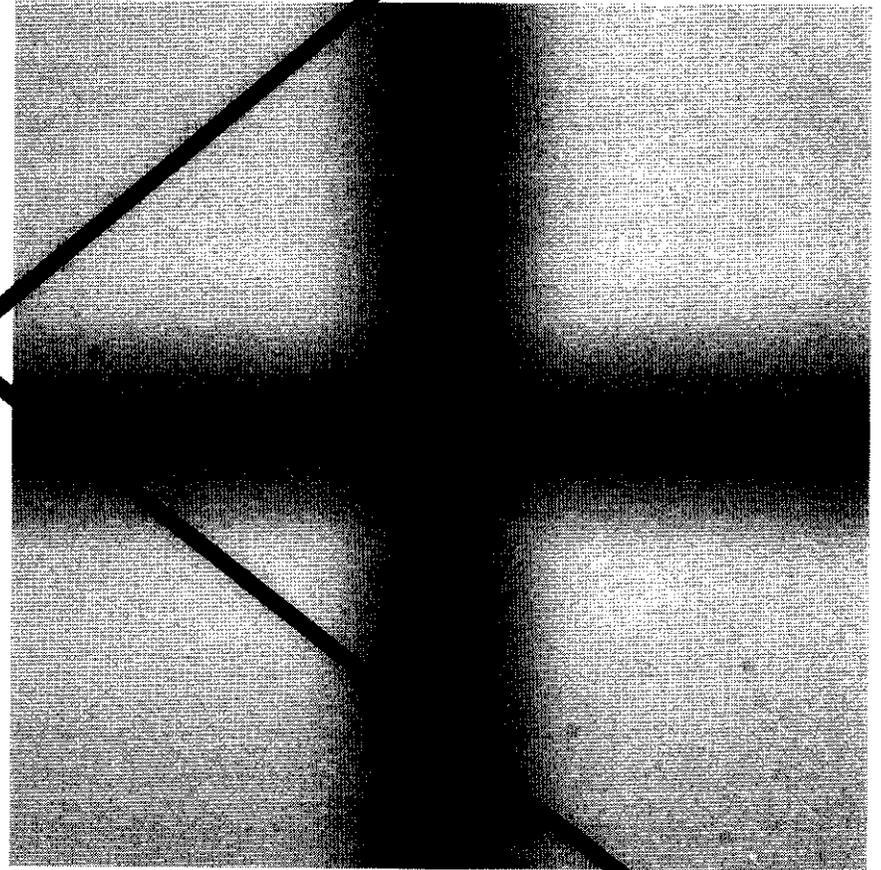
Images of fabricated spots (cont.)

3. Linear sinc^2



Raw image

4. Alignment cross (10 μm wide)

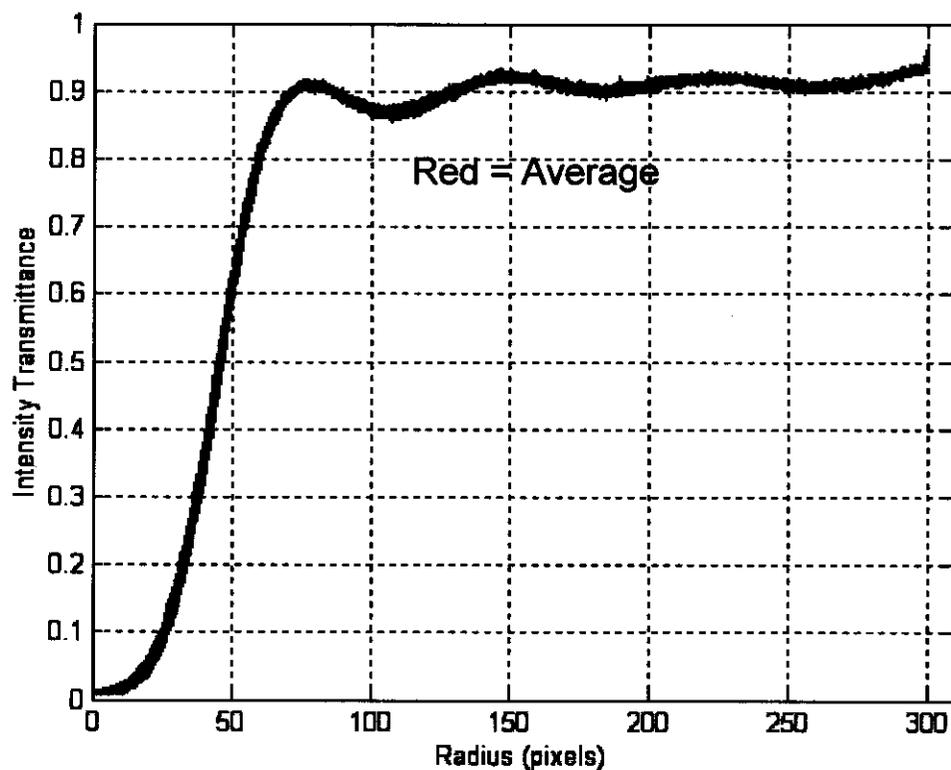
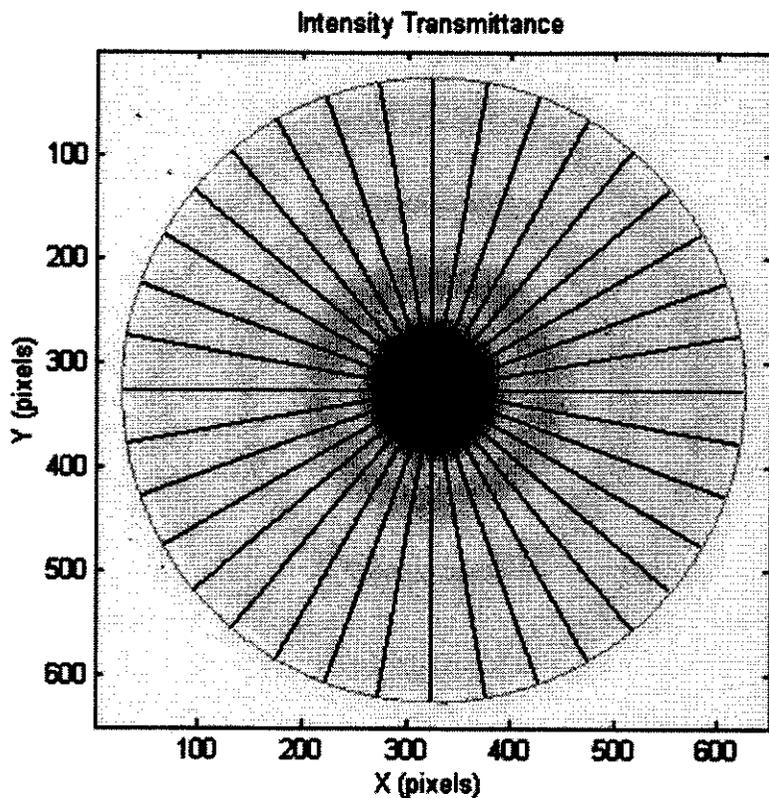


Raw image

Fabricated Occulting Spot Results

Comparison to design transmittance

- Circular sinc² – average transmittance along radial slices



Fabricated Occulting Spot Results

Comparison to design transmittance (cont.)

- Circular sinc^2
 - Comparison of radial slice average transmittance to design function
 - Errors can be explained by proximity effect and measurement error

